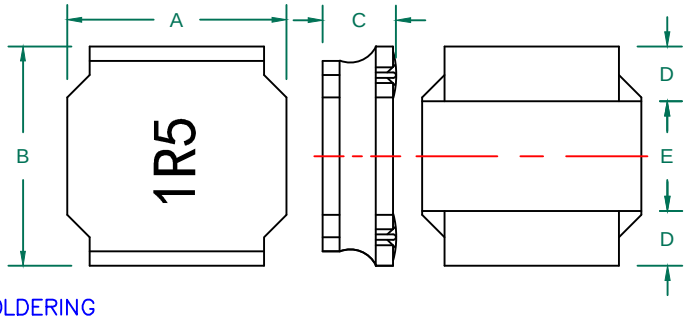
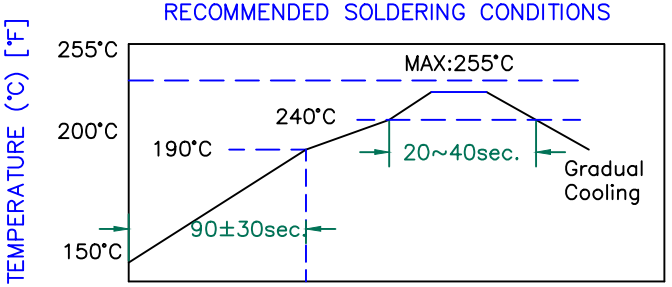
TYS50401R5N-10

PHYSICAL DIMENSIONS:

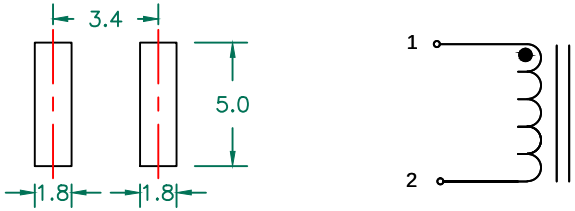
A	5.00	±	0.20
B	5.00	±	0.20
C	4.00	±	0.20
			0.30
D	1.60	±	0.30
E	1.80	±	0.30



RECOMMENDED SOLDERING CONDITIONS



LAND PATTERNS FOR REFLOW SOLDERING

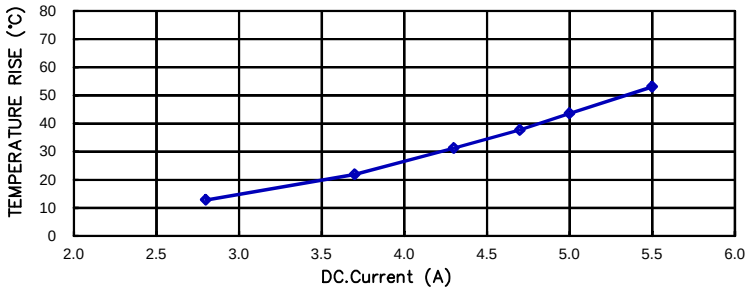


ELECTRICAL SPECIFICATION

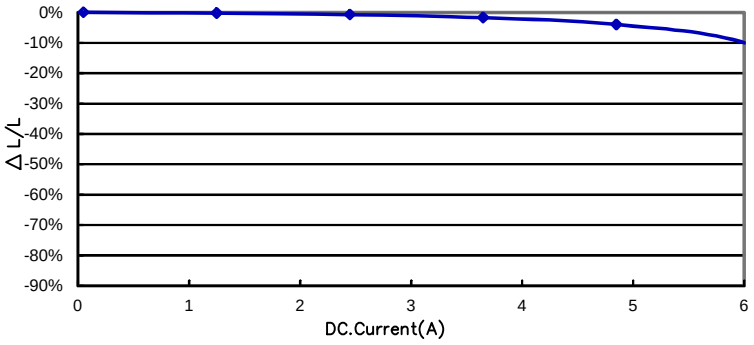
	Min	Nom	Max
INDUCTANCE (uH) L @ 100 KHz/1V ±30%	1.05	1.50	1.95
DCR (Ω)		0.015	0.018

Saturation Current(A)	6.30
SRF (MHz)	86
Temperature Rise Current (A)	4.30

CHARACTERISTICS OF TEMPERATURE RISE



CURRENT VS INDUCTANCE DROP IN RATES



RoHS

NOTES:

1. OPERATION TEMPERATURE RANGE: −40°C~+125°C (INCLUDING SELF−HEATING).

2. STORAGE TEMPERATURE RANGE (PACKAGING CONDITIONS): −10°C TO +40°C AND RH 70% (MAX.)

3. UNLESS OTHERWISE SPECIFIED, THE STANDARD ATMOSPHERIC CONDITIONS FOR MEASUREMENT/TEST AS:
   A. AMBIENT TEMPERATURE: 20±15°C.
   B. RELATIVE HUMIDITY: 65%±20%.

4. SATURATION CURRENT IS THE DC CURRENT AT WHICH THE INDUCTANCE DROPS OFF APPROXIMATELY 30% FROM ITS VALUE WITHOUT CURRENT.(AMBIENT TEMPERATURE 25±5°C)

5. TEMPERATURE RISE CURRENT (IRMS):
   DC CURRENT THAT CAUSES THE TEMPERATURE RISE (△T ≤40°C) FROM 25°C AMBIENT.

DIMENSIONS ARE IN mm .

REV	DESCRIPTION	DATE	INT
C	CHANGE DIMENSIONS C/D/E	08/18/16	QIU
B	CHANGE TEMP FROM −25°C~+125°C	12/21/12	QIU
A	ORIGINAL DRAFT	05/31/12	QIU

Laird

PROJECT/PART NUMBER:	REV	PART TYPE:	DRAWN BY:
TYS50401R5N−10	C	POWER INDUCTOR	QIU

DATE:	SCALE:	SHEET:
05/31/12	NTS	1 of 1

CAD # TYS50401R5N−10−C TOOL # −